

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	34154	semiconductor and (electrical adj connection)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:20
2	BRS	L2	6794	1 and die	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 10:17
3	BRS	L3	2263	2 and ((flip adj chip) or wirebond\$3)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:20
4	BRS	L4	3	3 and (first adj contact adj site) and (second adj contact adj site)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:24

	Type	L #	Hits	Search Text	DBs	Time Stamp
5	BRS	L5	40	3 and (first adj face) and (second adj face)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 11:49
6	BRS	L7	440	1 and (receiv\$3 with die) and ((flip adj chip) or wirebond\$3)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 13:04
7	BRS	L10	944	1 and 438/108,106,121,612,669.ccls.	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:13
8	BRS	L11	62	7 and 438/108,106,121,612,669.ccls.	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 12:02

	Type	L #	Hits	Search Text	DBs	Time Stamp
9	BRS	L12	215	1 and (bond adj pad) and (receiv\$3 with die) and ((flip adj chip) or wirebond\$3)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 13:05
10	BRS	L13	5888	438/108,106,121,612,669.ccls.	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:24
11	BRS	L14	20821	semiconductor and die and ((flip adj chip) or wire\$7)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:25
12	BRS	L15	5888	438/108,106,121,612,669.ccls.	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:25

	Type	L #	Hits	Search Text	DBs	Time Stamp
13	BRS	L16	1055	438/108,106,121,612,669.ccls. and semiconductor and die and ((flip adj chip) or wire\$7)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:47
14	BRS	L17	971	16 and pack\$5	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:48
15	BRS	L18	583	438/108,106,121,612,669.ccls. and semiconductor and die and ((flip adj chip) or wirebond)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 15:22
16	BRS	L19	549	18 and pack\$5	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:48

	Type	L #	Hits	Search Text	DBs	Time Stamp
17	BRS	L20	112	19 and (bottom adj surface) and (top adj surface)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:54
18	BRS	L21	144	438/108,106,121,612,669.ccls. and semiconductor and die and (flip adj chip) and (wire adj bond)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 15:23
19	BRS	L22	72	438/108,106,121,612,669.ccls. and semiconductor and die and (flip adj chip) and (wire adj bond) and (electric\$3 adj connection)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 15:24